

CUSTOMER: _____

DATE: _____

APPROVAL SPECIFICATION



PRODUCT NAME: Common Mode Choke

YOUR PART NO.:

OUR PART NO.: MGRC090505S250TL-2-LF

VERSION: V1.0

<p>RECEPTION</p> <p>THE SPECIFICATION HAS BEEN ACCEPTED.</p> <p>DATE:</p> <p>COMPANY:</p>		
CFMD	CHKD	RCVD

MANUFACTURING NAME

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CATALOG

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Component SPEC Version Record

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
1.0	2023.04.20	New released	/	Remo

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1. Scope

This specification applies to the MGRC090505 series of Common Mode Choke .

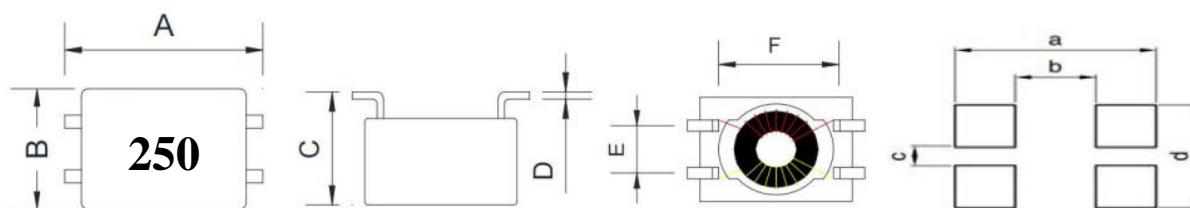
2. Product Identification

MGRC 090505 S 250 T L - 2 LF
① ② ③ ④ ⑤ ⑥ ⑦ ⑧

- ① Product Symbol (Wire wound Common choke)
- ② Dimensions (090505:9*5*5mm)
- ③ Winding Type (S for Sector Winding, B for Bifilar Winding)
- ④ Inductance Value (250:25*10⁰=25uH)
- ⑤ Packaging style (T: Taping ; B: Bulk)
- ⑥ Internal code
- ⑦ Number of signal lines
- ⑧ Lead Free

3. Appearance and Dimensions

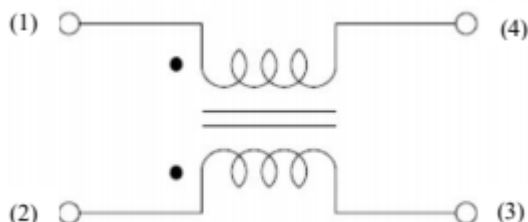
(1) Appearance , dimensions and recommended land pattern



unit:mm

Type	A	B	C	D	E	F
Dimension	9.5 Max.	6.0 Max.	5.2 Max.	0.3 Typ.	2.5 Typ.	5.5 Typ.
Type	a	b	c	d		
Dimension	10.2 Typ.	4.4 Typ.	1.34 Typ.	3.74 Typ.		

4. Electrical Schematic



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5.Testing Conditions

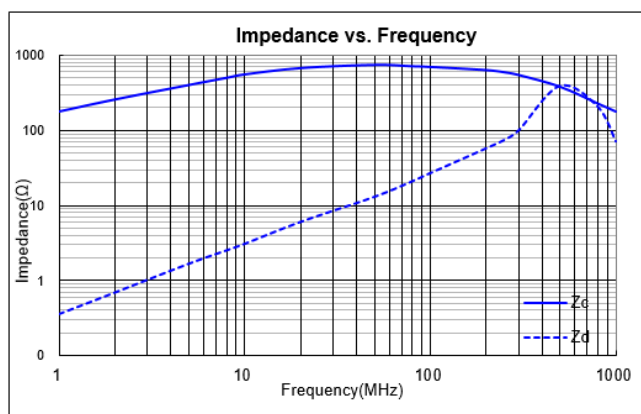
<Unless otherwise specified>,Temperature : 5 to 35°C, Humidity : 25 to 85% (RH)

<In case of doubt> Temperature : 20±2°C, Humidity : 60 to 75% (RH) ,Atmospheric Pressure : 86 to 106 kPa

6.Rating

Operating Temperature Range : -40°C~+125°C

Part No.	Inductance @0.1MHz,0.1 mA	Leakage Inductance@0. 1MHz,5mA	DCR (Ω)	Rated Current (A)	Vtest (Vdc 2s)
MGRC090505S250TL-2-LF	25 ± 30% μ H	1.4 μ H Typ.	0.11 Max.	0.80 Max.	250



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7. Electrical Performance

Impedance;

Impedance shall meet item 6 when measured on the condition of Table 1.

Table 1

Measuring Equipment	Impedance analyzer keysight E4982A or equivalent
Measuring Frequency	In the table
Measuring signal level	-13dBm
Measuring Fixture	keysight 16197A

DCR

D.C R shall meet item 6 when measured on the condition of Table 2.

Table 2

Measuring Equipment	LCR Meter HIOKI 3542 or equivalent
---------------------	------------------------------------

Rated Current

Temperature rise no more than 40°C against chip surface temperature 25°C when the allowable current (which is mentioned in item 6) is applied.

Table 3

Measuring Equipment	DC Power Supplier, Current Meter, Thermometer
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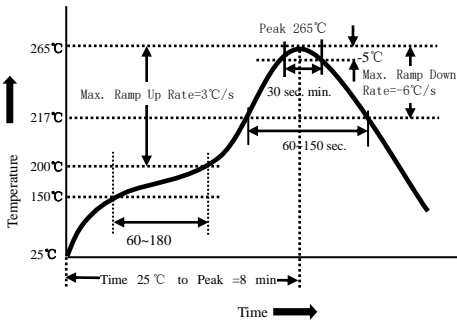
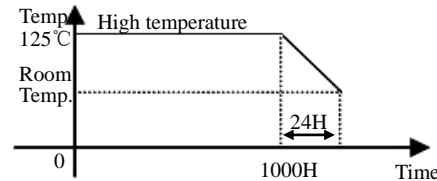
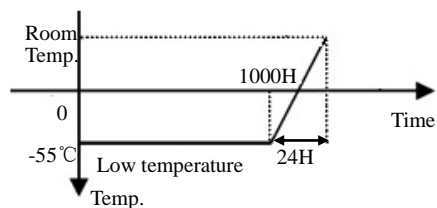
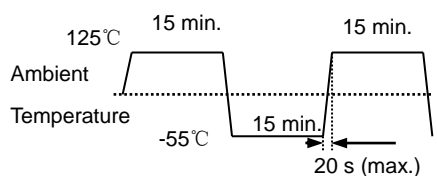
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8. Reliability

No.	Item	Requirements	Test Methods and Remarks	Reference	Sample Size
1	Solderability	Terminal area shall be at least 95% covered .	①Temperature: $240 \pm 5^{\circ}\text{C}$, flux 5-10 s. ②Sample immersion tin furnace $3 \pm 1\text{s}$. ③Sn/3.0Ag/0.5Cu	AEC-Q200 (J-STD-002)	15
2	Resistance to Soldering Heat	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	①The peak temperature: $260 \pm 5/-0^{\circ}\text{C}$. ②Reflow: 3 times. ③Temperature curve is as below: 	AEC-Q200 (MIL-STD-202 Method 210)	30
3	High Temperature Storage		①Temperature: $125 \pm 2^{\circ}\text{C}$. ②Time : 1000(+48,0) hours. ③Measurement at 24 ± 4 hours after test conclusion. 	AEC-Q200 (MIL-STD-202 Method 108)	77
4	Low Temperature Storage		①Temperature: $-55 \pm 2^{\circ}\text{C}$. ②Time : 1000(+48,0) hours. ③Measurement at 24 ± 4 hours after test conclusion. 	JESD22-A119	77
5	Thermal shock		①First -55°C for 15 minutes, last 125°C 15 minutes as 1 cycle. Go through 100 cycles. ②Max transfer time is 20 second. ③Measurement at 24 ± 4 hours after test conclusion. 	MIL-STD-202 Method 107	30

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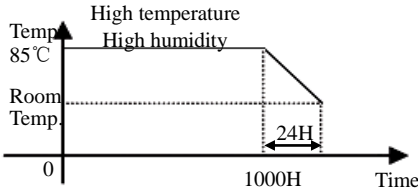
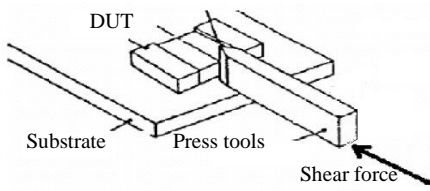
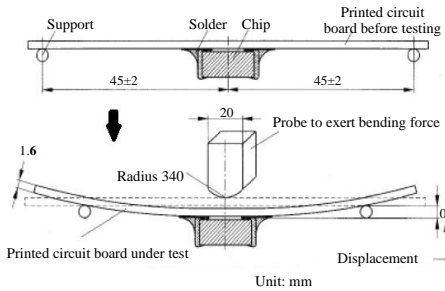
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6	Humidity Resistance	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	<p>①1000(+48,0) hours, 85°C/85%RH. ②Unpowered. ③Measurement at 24±4 hours after test conclusion.</p> 	AEC-Q200 (MIL-STD-202 Method 103)	77
7	Terminal Strength	No case deformation or change in appearance.	<p>①The test samples shall be soldered to the board. ②17.7N, 60±1s</p> <p>Radius 1.5mm</p> 	-	30
8	Board Flex	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	<p>①Part mounted on a 100mm*40mm FR4 PCB board, which is 1.6mm thick and as a Layer-thickness 35 μm ± 10 μm. ②Bending speed is 1mm/s. ③Keeping the P.C Board 2 mm minimum for 60 seconds.</p>  <p>Unit: mm</p>	AEC-Q200 (AEC-Q200-005)	30
9	Vibration	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	<p>10~2000Hz,5g,20min/Cycle,4 hours in each 3 mutually perpendicular directions (total of 12 hours)</p>	AEC-Q200	30

No.	Item	Requirements	Test Methods and Remarks	Reference	Sample Size
10	Loading at High Temperature	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	①Temperature: $125 \pm 2^\circ\text{C}$. ②Time : 1000(+48,0) hours. ③Proper current. ④Measurement at 24 ± 4 hours after test conclusion.	AEC-Q200 (MIL-PRF-27)	77
11	Loading at Damp Heat	(1) No case deformation or change in appearance. (2) $ \Delta L/L_0 \leq 20\%$	①Temperature: $60 \pm 2^\circ\text{C}$, Humidity: 90% to 95% RH ; ② Duration: 1000(+48,0) hours ③Applied current: Rated current. ④Measurement at 24 ± 4 hours after test conclusion.	AEC-Q200	77

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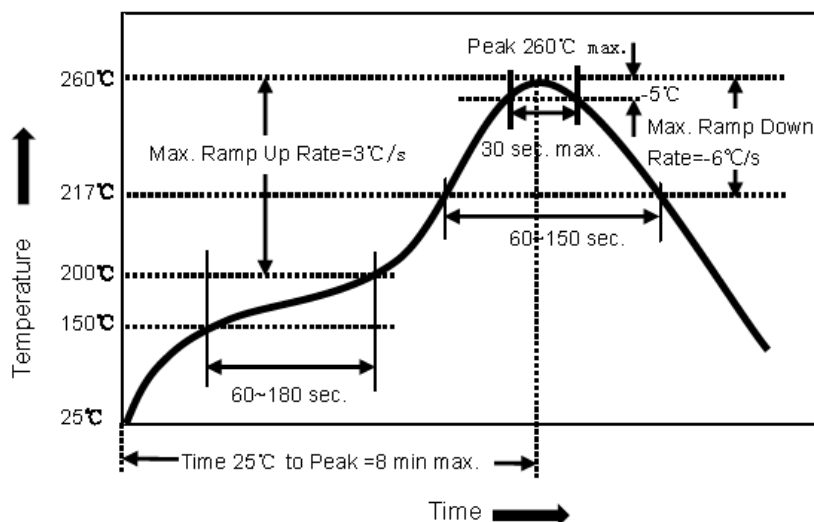
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9. Recommended Soldering Conditions

(1) Reflow soldering conditions



*Above reflow soldering curve is from J-STD-020D.

- Exceeding solder volume may cause the failure of mechanical or electrical performance.
- Before soldering, please ensure that the solder should not adhere to the wire part of chip.
- Please pay particular attention to whether there is flux remaining on surface of the wire part of chip after subjected to reflow soldering since this may causing short circuit of parts.

(2) Solder Volume

Solder shall be used not to exceed as shown below.

- Accordingly increasing the solder volume, the mechanical stress to chip is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.
- Before soldering, please ensure that the solder should not adhere to the wire part of chip.
- Please pay particular attention to whether there is flux remaining on surface of the wire part of chip after subjected to reflow soldering since this may causing short circuit of parts.

(3) Iron soldering

The following conditions must be strictly followed when using a soldering iron.

①

Pre-heating	150°C, 1 minute
Tip temperature	350°C max
Soldering iron output	30w max
End of soldering iron	Φ 1mm max
Soldering time	3 seconds max

② Don't touch the coil core directly with the top of the iron

③ In the welding process, the electric iron cannot bump into the enamel-insulated wire, lest components should have evidence of damage.

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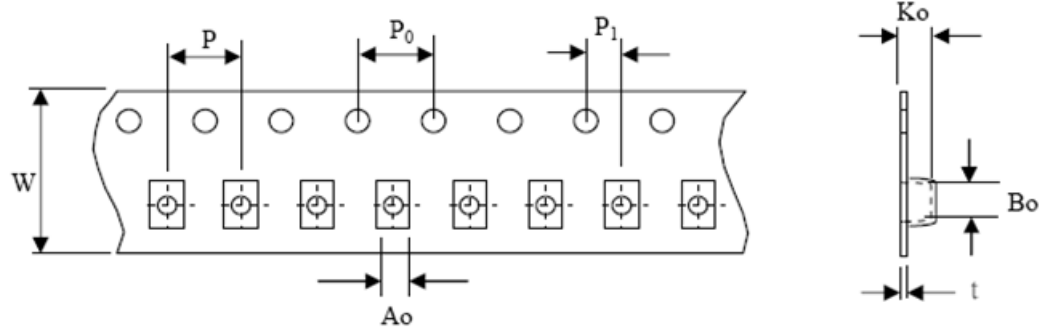
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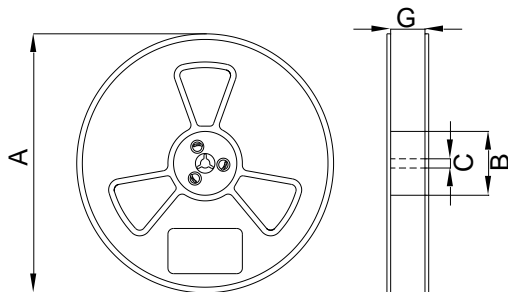
10. Packaging Information

(1) Dimension of tape (Unit: mm)



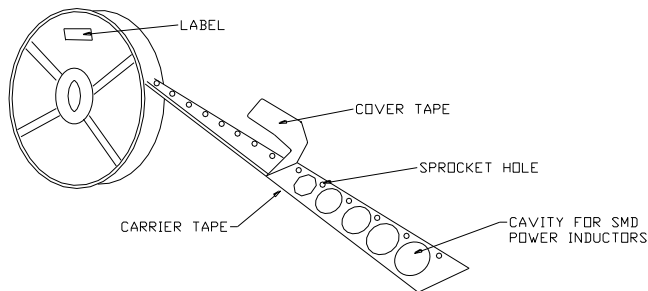
Symbol	W	P	P ₀	P ₁	A ₀	B ₀	K ₀	t
Dimension	16.0	8	4.0	2.0	5.8	9.7	5.5	0.30

(2) Dimension of reel (Unit: mm)



Symbol	Dimension
A	330
B	100
C	13
G	16

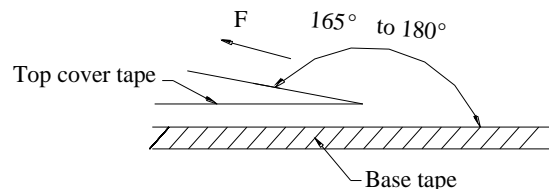
(3) Taping figure and drawing direction



(4) Packaging quantities: 1000 PCS/Reel.

(5) Peeling strength of cover tape:

The force tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions.



Room Temp. (°C)	Room Humidity (%)	Room aim (hpa)	Peel Speed mm/min
5-35	45-85	860-1060	300

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11. Storage

- a. The solder ability of the external electrode may be deteriorated if packages are stored where they are exposed to high temperature or high humidity. Besides, to ensure packing material's good state, packages must be stored at -40°C to 85°C and 15% ~85%RH.
- b. The solder ability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H₂S).
- c. Packaging materials may deform if packages are exposed directly to sunlight.
- d. Minimum packages, such as polyvinyl heat-seal packages shall not be opened until they are used. If opened, use the reels as soon as possible.
- e. Solderability shall be guaranteed for 12 months from the date of delivery on condition that they are stored at the environment specified in specification. For those parts, which passed more than the time shall be checked solder-ability before use.

12. Transportation

The cases shall not be damaged, destroyed and rained on.

13. Warning and Attentions

(1) Precautions on Use

- a. Always wear static control bands to protect against ESD.
- b. Any devices used (soldering iron, measuring instruments) should be properly grounded.
- c. Use non-magnetic tweezers when handing the chips.
- d. Pre-heating when soldering, and refer to the recommended condition specified in specification.
- e. Don't apply current in excess of the rated current value. It may cause damage to components due to over-current.
- f. Keep clear of anything that may generate magnetic fields such as speakers, coils.
- g. When soldering, the electrical characteristics may be varied due to hot energy and mechanical stress.
- h. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150° C.
- i. When mount chips with adhesive in preliminary assembly, do appropriate check before the soldering stage, i.e., the size of land pattern, type of adhesive, amount applied, hardening of the adhesive on proper usage and amounts of adhesive to use.
- j. Mounting density: Add special attention to radiating heat of products when mounting other components nearby. The excessive heat by other products may cause deterioration at joint of this product with substrate.
- k. Since some products are constructed like an open magnetic circuit, narrow spacing between components may cause a malfunction.
- l. Please do not give the product any excessive mechanical shocks in transportation.
- m. Please do not touch wires by sharp terminals such as tweezers to avoid causing any damage to wires.
- n. Please do not add any shock and power to the soldered product to avoid causing any damage to chip body.
- o. Please do not touch the electrodes by naked hand as the solderability of the external electrodes may deteriorate by grease or oil on the skin.

(2) PCB Bending Design

The following shall be considered when designing and laying out PCB's.

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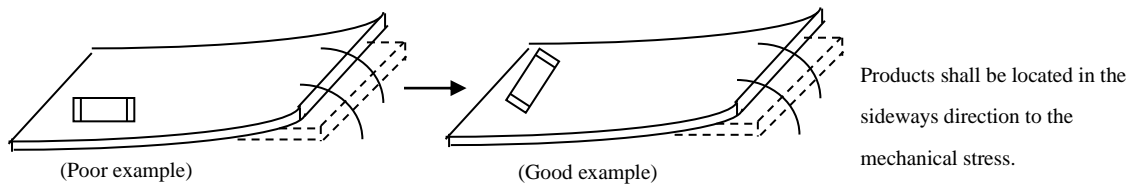
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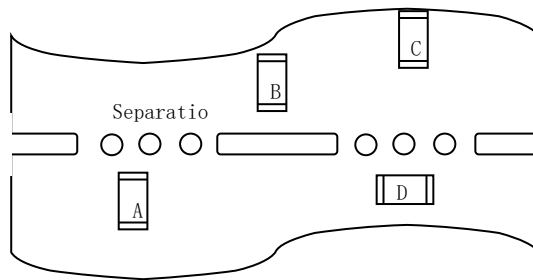
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1. PCB shall be designed so that products are not subjected to the mechanical stress from board warp or deflection.



2. Products location on PCB separation.



Product shall be located carefully because they may be subjected to the mechanical stress in order of $A > C = B > D$.

3. When splitting the PCB board, or insert (remove) connector, or fasten thread after mounting components, care is required so as not to give any stress of deflection or twisting to the board. Because mechanical force may cause deterioration of the bonding strength of electrode and solder, even crack of product body. Board separation should not be done manually, but by using appropriate devices.

(3) Recommended PCB Design for SMT Land-Patterns

When chips are mounted on a PCB, the amount of solder used (size of fillet) and the size of PCB Land-Patterns can directly affect chip performance. Therefore, the following items must be carefully considered in the design of solder land patterns.

- a. Please use the PCB pad and solder paste we recommend, and contact us in advance if they need to be changed.
- b. The amount of solder applied can affect the ability of chips to withstand mechanical stresses which may lead to breaking or cracking. Therefore, when designing land-patterns it is necessary to consider the appropriate size and configuration of the solder pads which in turn determines the amount of solder necessary to form the fillets.
- c. When more than one part is jointly soldered onto the same land or pad, the pad must be designed that each component's soldering point is separated by solder-resist.

Recommended land dimensions please refer to product specification.

14. Cleaning

Products shall be cleaned on the following conditions:

(1) Cleaning temperature shall be limited to 60°C Max. (40°C Max. for IPA)

(2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and PCB.

Power: 20W/l Max. Frequency: 28 KHz to 40 KHz Time: 5 minutes Max

(3) Cleaner

a. Alcohol type cleaner

Isopropyl alcohol (IPA)

b. Aqueous agent

Surface Active Agent Type (Clean through-750H)

Hydrocarbon Type (Techno Cleaner-335)

Higher Alcohol Type (Pine Alpha ST-100S)

c. There shall be no residual flux and residual cleaner after cleaning.

In the case of using aqueous agent, product shall be dried completely after rinse with de-ionized water in order to remove the cleaner.

d. Some products may become slightly whitened. However, product performance or usage is not affected.

e. Please take care of winding part while cleaning.

f. After cleaning, parts could be subjected to the next reflow soldering till the solvent remaining on surface of parts being volatilized.